

REMARKS

The Action mailed on March 22, 2006 was indicated final. However, the Action can not be made final under MPEP 706.07(a). Namely, in the present application, the examiner introduced a new ground of rejection that is neither necessitated by applicant's amendment of the claims nor based on information submitted in an information disclosure statement.

Under the circumstances, claims have been amended as in the first Action. Please withdraw finality, and examine the claims as non-final Action.

On page 3 of the Action, claims 1-12 were rejected under 35 U.S.C. 102(b) as being anticipated by Hayashi.

In view of the rejection, claims 1 and 3 have been amended, and new claims 13-15 have been filed.

In claim 1, it is clarified that a micro power converter comprises, in part, a plurality of thin film magnetic induction components electrically connected to the semiconductor integrated circuit and arranged to be spaced apart from each other with a gap therebetween, each of said thin film magnetic induction components comprising a magnetic insulation substrate and a coil conductor formed on the magnetic insulation substrate.

In the present invention, the micro power converter with the multiple outputs can be made compact, i.e. small size, thickness and mounting area.

In particular, as recited in new claim 13, the coil conductor comprises upper and lower conductor portions formed on and under the magnetic insulation substrate, and connecting conductors for connecting the upper and lower conductor portions to form one conductor.

In the Action, it was held that "said plurality of thin film magnetic induction components being spaced apart from each other with a gap therebetween (0004 and layer 5)."

The paragraph 0004 of Hayashi is explained as follows:

"[Subject to be solved by the Invention] The structure of a plan type magnetic induction element to be mounted on a conventional small electric converter is formed, as shown in Fig. 4, such that a thin magnet layer 54 is formed on a thin coil 56, and spaces of the conduction members forming the thin coil 56 are filled with insulation filler (polyimide filler 55). In the drawing, 51 is silicon substrate, 52 is IC protection layer, 53 is lower insulation layer, 57 is upper insulation layer, 58 is magnetic thin layer, 61 is conventional plan type magnetic conductor element, and 62 is protection layer."

The layer 5 referred to by the Examiner is polyimide filler filled between the spaces of the conductor element spirally arranged.

Therefore, in Hayashi, the magnetic conductor element 61 or coil 6 is arranged spirally, and the filler 55 or 5 is filled in the space of the coil 6. In claim 1, it is defined that each of the thin film magnetic induction components comprises a magnetic insulation substrate and a coil conductor formed on the magnetic insulation substrate. The structure in claim 1 is not disclosed in Hayashi.

On page 3 of the Action regarding claim 3, it was held in part that "each of said thin film magnetic induction components includes one of said magnetic insulation substrates (8), a coil conductor formed on the one magnetic insulation substrate (6)."

However, numeral 8 referred to by the Examiner is a thick ferrite magnetic plate for preventing warping of the silicon substrate 1. The coil conductor is not formed on the magnetic insulation substrate, difference from claim 1.

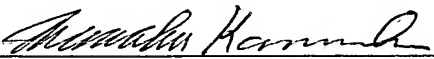
Therefore, claim 1 now clearly defined in the amendment is not anticipated by Hayashi.

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If some correction or clarification is required, please contact the undersigned agent.

Reconsideration and allowance are earnestly solicited.

Respectfully Submitted,

By 
Manabu Kanesaka
Reg. No. 31,467
Agent for Applicants

1700 Diagonal Road, Suite 310
Alexandria, VA 22314
(703) 519-9785